ABSTRACT

IMAGING OPERATIONS FOR A WIRE BONDING SYSTEM

A method of imaging a feature of a semiconductor device is provided. The method includes the steps of: (a) imaging a first portion of a semiconductor device to form a first imaged portion; (b) imaging a subsequent portion of the semiconductor device to form a subsequent imaged portion; (c) adding the subsequent imaged portion to the first imaged portion to form a combined imaged portion; and (d) comparing the combined imaged portion to a reference image of a feature to determine a level of correlation of the combined imaged portion to the reference image.

Fig. 4